



PRODUCT DESCRIPTION

Tflex[™] 700 is a 5 W/mK soft gap filler thermal interface material with great thermal performance and high compliancy. The soft interface pad conforms to component topography, resulting in little or no stress on the components and mating chassis or parts.

Unique silicone and ceramic filler technology allows a combination of high compliancy and high thermal performance. Tflex[™] 700 is stable from -40°C thru 200°C and meets UL 94V0 flame rating. Naturally tacky, it requires no additional adhesive coating which inhibits thermal performance.

FEATURES AND BENEFITS

- Thermal conductivity 5.0 W/mK
- Highly compliant
- Low thermal resistance even at low pressure
- Available in thicknesses from 0.5mm thru 5.0mm (0.020" thru 0.200") in 0.25mm (0.010") increments
- Naturally tacky for adhesion during assembly and transport

TYPICAL PROPERTIES

PROPERTY	TYPICAL VALUE	TEST METHOD
Construction	Filled Silicone Sheet	
Color	Dark Grey	Visual
Thermal Conductivity	5.0 W/mK	Hot Disk
Hardness (3 sec)	78 (<1mm) 66 (>1mm)	ASTM D2240
Specific Gravity	1.73	Helium Pycnometer
Flammability	94V0	UL 94
Operating Temperature	-40°C to 200°C	
Outgassing TML	1.0%	ASTM E595
Outgassing CVCN	0.13%	ASTM E595
Thickness Range	0.5mm - 5.0mm (0.020" - 0.200")	

Americas: +1.800.843.4556

Europe: +49.8031.2460.0

Asia: +86.755.2714.1166

THR-DS-Tflex 700 17June16

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

Any information furnished by Laird and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird materials rests with the end user, since Laird and its agents cannot be aware of all potential uses. Laird makes no warranties as to the fitness, merchantability or suitability of any Laird materials or products for any specific or general uses. Laird, Laird Technologies, Inc or any of its affiliates or agents shall not be liable for incidental or consequential damages of any kind. All Laird products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2015 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird or any third party intellectual property rights. A15955-00 Rev ARAS-B, 05/04/2016